

LEAD PARTICLE ENTRAPMENT COMPOUND (LEPEC)

DESCRIPTION

1. GENERAL

1.01 This sections describes lead particle entrapment compound (LEPEC).

Lead particle entrapment compound may be referred to as Le.P.E.C." in some sections of the Bell System Practices; however, LEPEC is the correct acronym.

1.02 If this section is reissued, the reasons for reissue will be listed in this paragraph.

2. DESCRIPTION

2.01 LEPEC is a cream-like substance that, when applied to lead surfaces during carding, will catch and contain lead particles that would otherwise become airborne. LEPEC acts as a flux for soldering, a wetting agent to eliminate lead dust, and an emulsion to catch lead particles.

2.02 Removing excess LEPEC from a cleaned area with a clean, dry rag is sufficient preparation for soldering and wiping operations. Since stearine is a component of LEPEC, it is not necessary to apply additional stearine to a cleaned area to protect against oxidation.

2.03 Where sheath repair sleeving will be installed and is intended to maintain air pressure, or where sealing tape will be applied to the cleaned area, residual LEPEC should be removed with B cleaning fluid to provide for proper adhesion.

2.04 LEPEC is available in 8-ounce tubes and may be ordered as: (Qty)
Tube Compound, Entrapment, Particle, Lead.

2.05 The use of LEPEC is required when cleaning lead surfaces. Refer to Sections 632-315-100, 633-200-201, and 644-200-005 for instructions on the use of LEPEC.